

TIF™200 Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to the coating of the very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the separate elements or even the entire PCB, which in effect enhances the efficiency and life-time of the heat-generating electronic components.



热传导间隙填充材料

TIF™200 系列热传导界面材料是填充发热器件和散热片或金属底座之间的空气间隙，它们的柔性、弹性特征使其能够用于覆盖非常不平整的表面。热量从分离器件或整个PCB传导到金属外壳或扩散板上，从而能提高发热电子组件的效率和使用寿命。

Features

- › Good thermal conductive: **1.0W/mK**
- › Naturally tacky needing no further adhesive coating
- › Soft and Compressible for low stress applications
- › Available in varies thickness

Application

- › Cooling components to the chassis of frame
- › High speed mass storage drives
- › RDRAM memory modules
- › Micro heat pipe thermal solutions
- › Automotive engine control units
- › Telecommunication hardware
- › Handheld portable electronics
- › Semiconductor automated test equipment (ATE)

特性

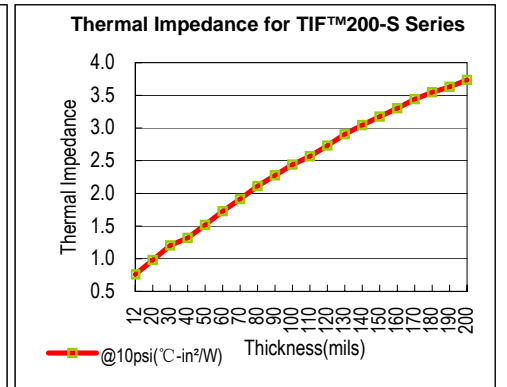
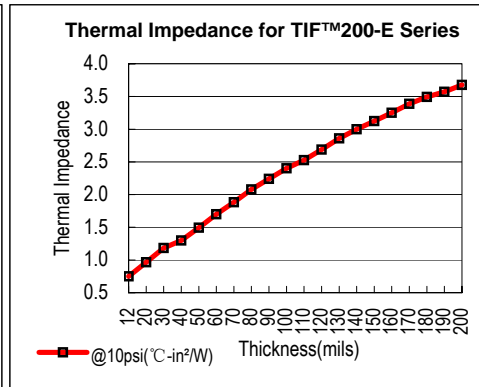
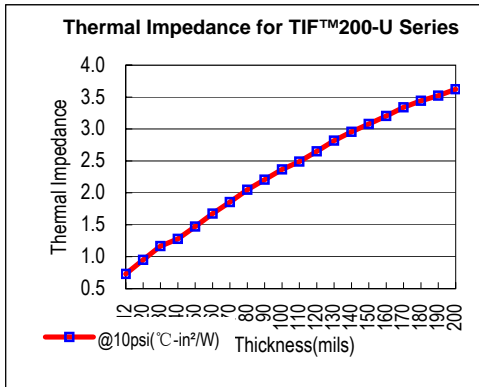
- › 良好的热传导率: **1.0W/mK**
- › 带自粘而无需额外表面粘合剂
- › 高可压缩性,柔软兼有弹性,适合于在低压力应用环境
- › 可提供多种厚度选择

应用

- › 散热器底部或框架
- › 高速硬盘驱动器
- › RDRAM 内存模块
- › 微型热管散热器
- › 汽车发动机控制装置
- › 通讯硬件
- › 便携式电子装置
- › 半导体自动试验设备

Typical Properties of TIF™200 Series TIF™200 系列特性表

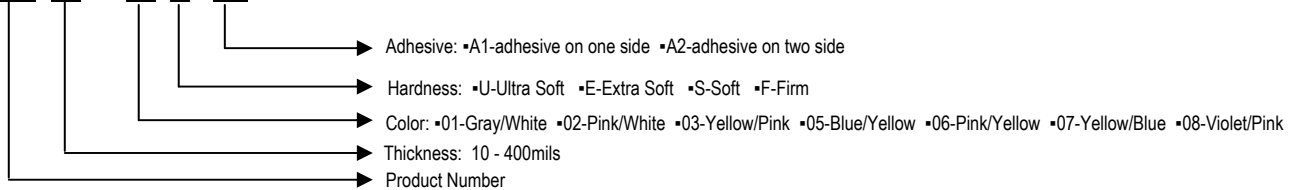
Product Name(產品名稱)	TIF™200-U	TIF™200-E	TIF™200-S	Visual	Thickness (厚度)	Thermal Impedance (熱阻) @10psi(°C-in²/W)		
						TIF™200-U	TIF™200-E	TIF™200-S
Color(顏色)	Various (各色)			Visual				
Construction & Composition (結構&成分)	Ceramic filled silicone elastomer (陶瓷填充矽橡膠)			***	12 mils 0.304 mm	0.73	0.75	0.76
Specific Gravity(比重)	1.75 g/cc			ASTM D297	20 mils 0.508 mm	0.95	0.97	0.98
Heat Capacity(熱容積)	1 l/g-K			ASTM C351	30 mils 0.762 mm	1.17	1.18	1.20
Hardness(硬度)	5	10	15	ASTM 2240	40 mils 1.016 mm	1.28	1.30	1.32
					50 mils 1.270 mm	1.47	1.49	1.52
Tensile Strength, (抗張強度)	425 psi			ASTM D412	60 mils 1.524 mm	1.68	1.70	1.73
					70 mils 1.778 mm	1.86	1.88	1.91
Continuous Use Temp (使用溫度範圍)	-50 to 200°C			***	80 mils 2.032 mm	2.05	2.08	2.11
					90 mils 2.286 mm	2.21	2.24	2.28
Dielectric Breakdown Voltage (擊穿電壓)	>5500 VAC			ASTM D149	100 mils 2.540 mm	2.37	2.40	2.44
					110 mils 2.794 mm	2.49	2.53	2.57
Dielectric Constant (介電常數)	5.5 MHz			ASTM D150	120 mils 3.048 mm	2.65	2.69	2.73
					130 mils 3.302mm	2.82	2.86	2.91
Volume Resistivity (體積電阻率)	4.0X10" Ohm-meter			ASTM D257	140 mils 3.556 mm	2.95	3.00	3.05
					150 mils 3.810 mm	3.08	3.12	3.17
Flame Rating(防火等級)	94 V0			equivalent UL	160 mils 4.064 mm	3.20	3.25	3.30
					170 mils 4.318 mm	3.34	3.39	3.44
Thermal Conductivity (導熱率)	1.0 W/m-K			ASTM D5470	180 mils 4.572 mm	3.44	3.49	3.55
					190 mils 4.826 mm	3.52	3.57	3.63
					200 mils 5.080 mm	3.62	3.68	3.73



Product Identification

Example: TIF™280-08U-A1

TIF2 80 - 08 U - A1



Gap Fillers | Phase Change Materials | Thermally Conductive Insulators | Thermally Conductive PCB Materials | Greases | Thermally Conductive Adhesive Tapes